

**ABSTRACT**

A process for forming bumps on electrode pads performs at least the following steps (a) to (d) for a wiring board including a substrate and a plurality of electrode pads:

- 5       (a) a step of forming a laminated two-layer film on the wiring board and forming a pattern of apertures at positions corresponding to the electrode pads, the laminated two-layer film including a lower layer containing an alkali-soluble radiation-nonsensitive resin composition and an upper layer  
10       containing a negative radiation-sensitive resin composition;
- (b) a step of filling a low-melting metal in the aperture pattern;
- (c) a step of reflowing the low-melting metal by pressing or heating to form bumps; and
- 15       (d) a step of peeling and removing the laminated two-layer film from the board. The laminated film including two layers with different properties permits high resolution and easy peeling.